

Pre applied high performance thermal paste (silicone based)

TP(HPTP)SEMITOP_E1

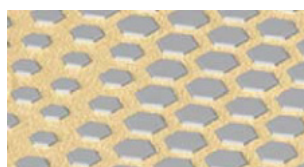
Features*

- New high performance thermal paste
- Superior heat dissipation
- Inhomogeneous honeycomb structure
- Optimized thickness of thermal paste layer
- High process reliability due to automated screen printing process

Characteristics					
Symbol	Conditions	min.	typ.	max.	Unit
Characteristics of printing process					
W_{tp}	material weight	140	170	200	mg
Storage conditions					
t_{stg}	storage time			12	month
T_{stg}	storage temperature	5		40	°C
RH_{stg}	storage humidity	10		85	%
TIM material characteristic					
γ_{tp}	specific gravity		4.2		g/cm ³
R_{tp}	resistivity		$1.2 \cdot 10^{12}$		Ω/cm
E_{tp}	dielectric strength		3		kV/mm
λ_{tp}	thermal conductivity		2.5		W/(mK)

*IMPORTANT INFORMATION AND WARNINGS

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honeycomb structure